



ADHESIVES AND SEALANTS LAB

LABORATORY INFORMATION FACT SHEET

CONTACT US:

Technology Transfer Office

Email: usarmy.pica.devcom-ac.mbx.t2@army.mil

v.02

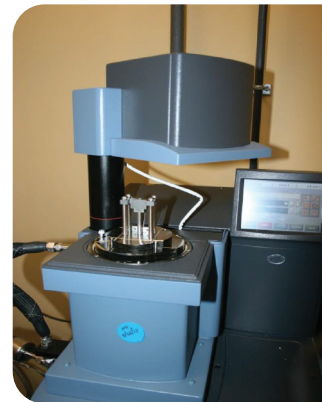
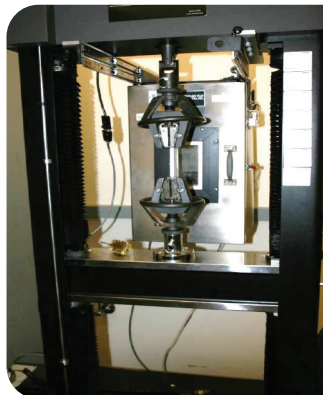


The Adhesives and Sealants Lab, a part of the Organic Materials Technology Branch, is positioned to provide DEVCOM's Armaments Center armaments development and engineering organizations with consultation, laboratory services and rapid prototyping solutions on base.

TECHNOLOGY/FACILITY DESCRIPTION:

Adhesives and sealants capabilities include joint design/fabrication, surface preparation technology, durability studies,

energetic compatibility testing, material characterization, mechanical testing, material replacement studies, product verification, specification development, process analysis and failure analysis. Unique engineering initiatives in the adhesives/sealants field include the development of an alternate case mouth waterproofing sealant material/process for ammunition applications and the development and transition of environmentally-compliant, sol-gel surface preparations for structural adhesive bonding and coating applications on metallic substrates.



EQUIPMENT AND EXPERTISE AVAILABLE:

- Abrasive Media Cabinet
- Binks Spray Priming System
- UV Curing Apparatus
- 50 Ton Adhesive Bonding Press
- Temperature/Humidity Chambers
- Instron Mechanical Test Frames
- Thermogravimetric Analyzer (TGA)
- Differential Scanning Calorimeter (DSC)
- Fourier Transform Infrared (FTIR) Spectrometer